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(12) **United States Design Patent**  
**Iida et al.**

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(54) **ARM FOR WAFER TRANSPORTATION FOR MANUFACTURING SEMICONDUCTOR**

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(\*) Notice: This patent is subject to a terminal disclaimer.

(\*\*) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**  
USPC ..... D13/182; 118/500, 725, 728, 729;  
294/103.1; 414/217, 222.01, 416.03,  
414/941  
See application file for complete search history.

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(57) **CLAIM**

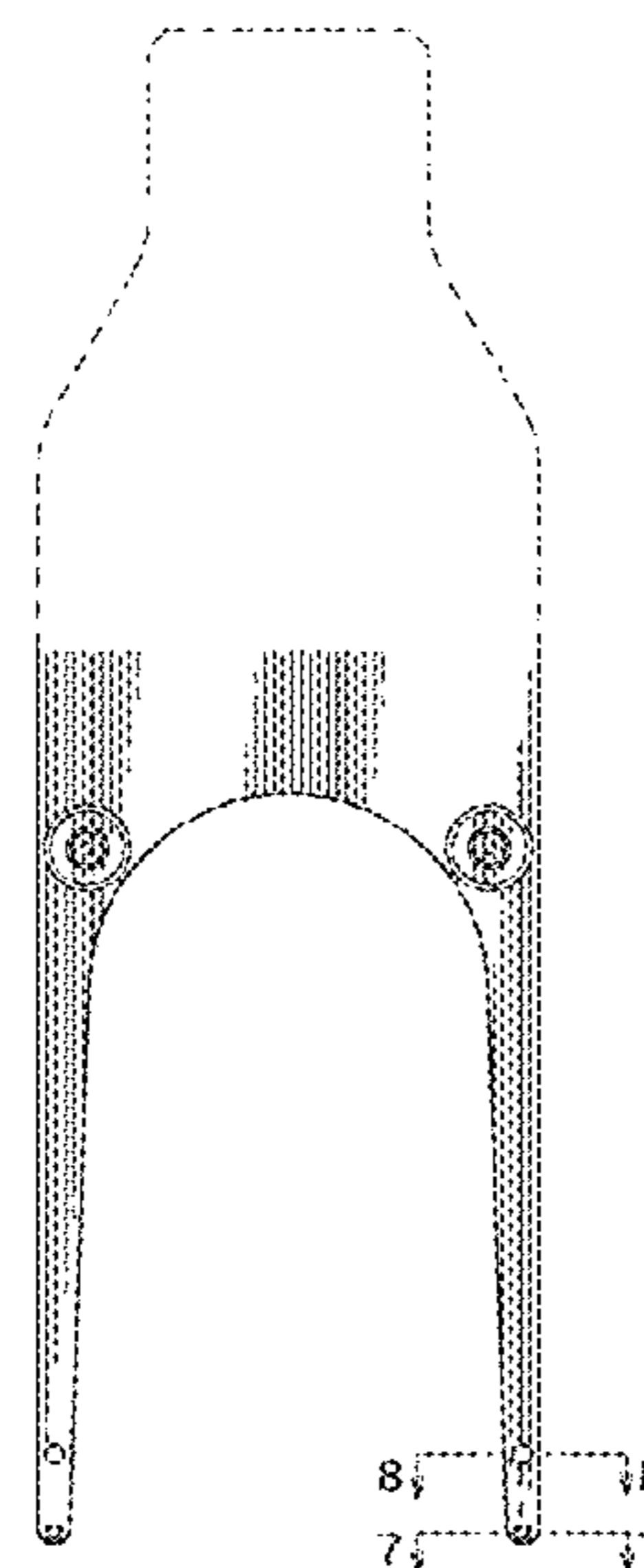
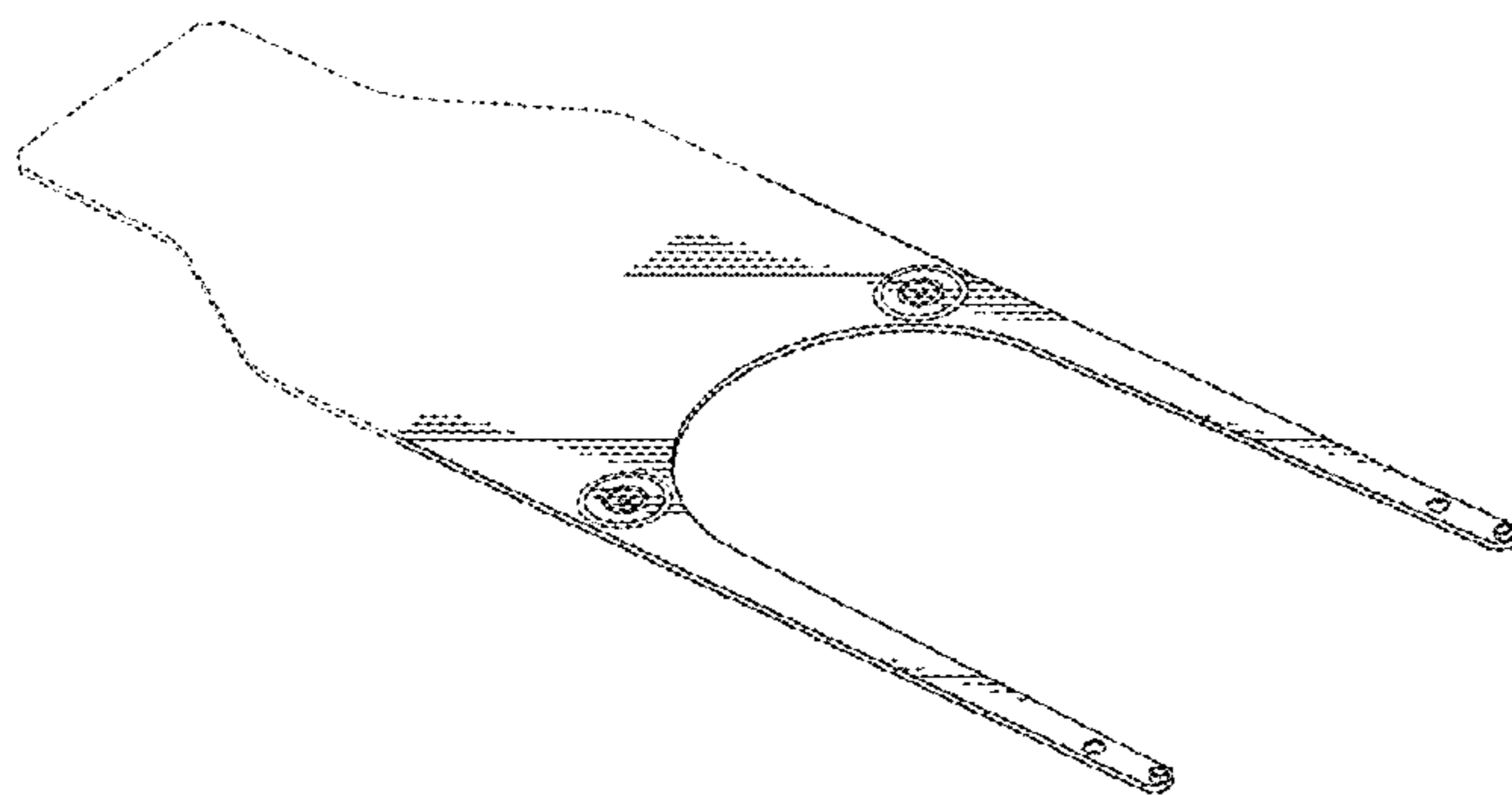
The ornamental design for arm for wafer transportation for manufacturing semiconductor, as shown and described.

**DESCRIPTION**

FIG. 1 is perspective view of an arm for wafer transportation for manufacturing semiconductor showing our new design; FIG. 2 is a top plan view thereof; FIG. 3 is a bottom plan view thereof; FIG. 4 is a front view thereof; FIG. 5 is a rear view thereof; FIG. 6 is a left side view thereof, the right side view being a mirror image; FIG. 7 is an enlarged sectional view taken along line 7-7 of FIG. 2; and, FIG. 8 is an enlarged sectional view taken along line 8-8 of FIG. 2.

The broken lines shown in the drawings represent portions of the arm for wafer transportation for manufacturing semiconductor that form no part of the claimed design.

**1 Claim, 5 Drawing Sheets**



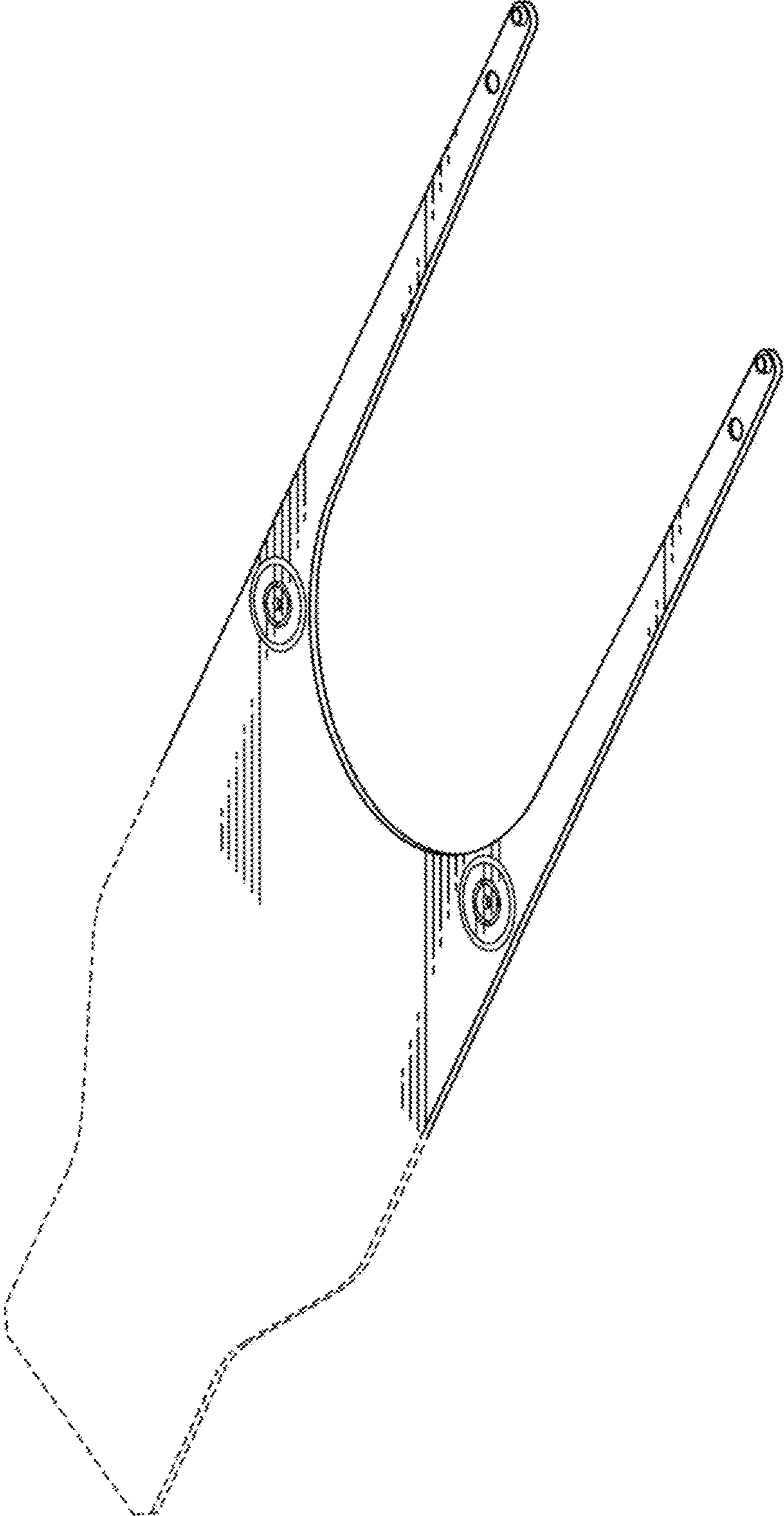


FIG. 1

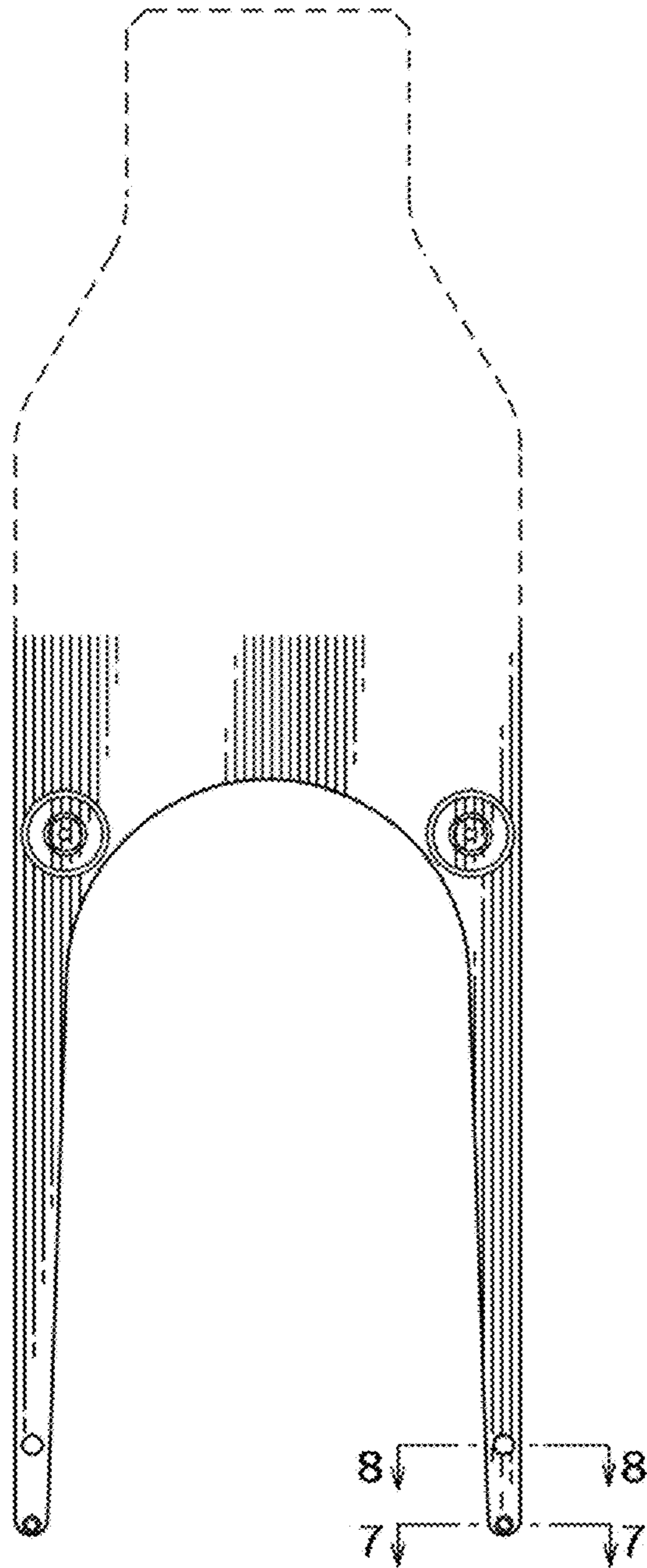


FIG. 2

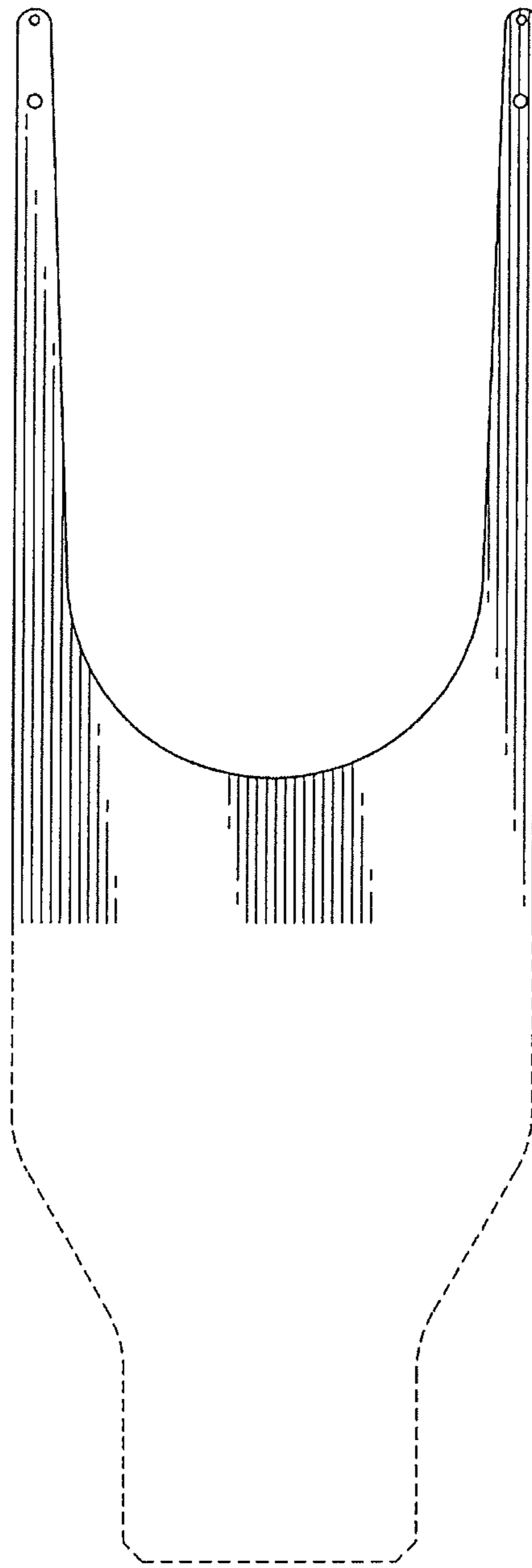


FIG. 3



FIG. 4

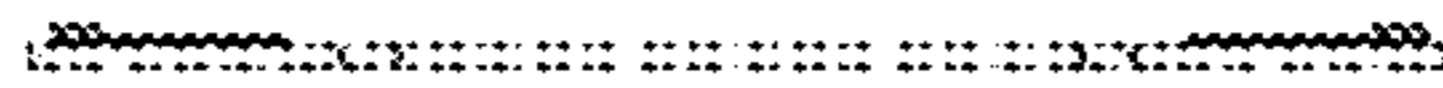


FIG. 5

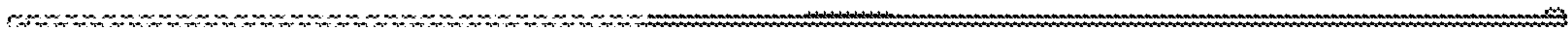


FIG. 6

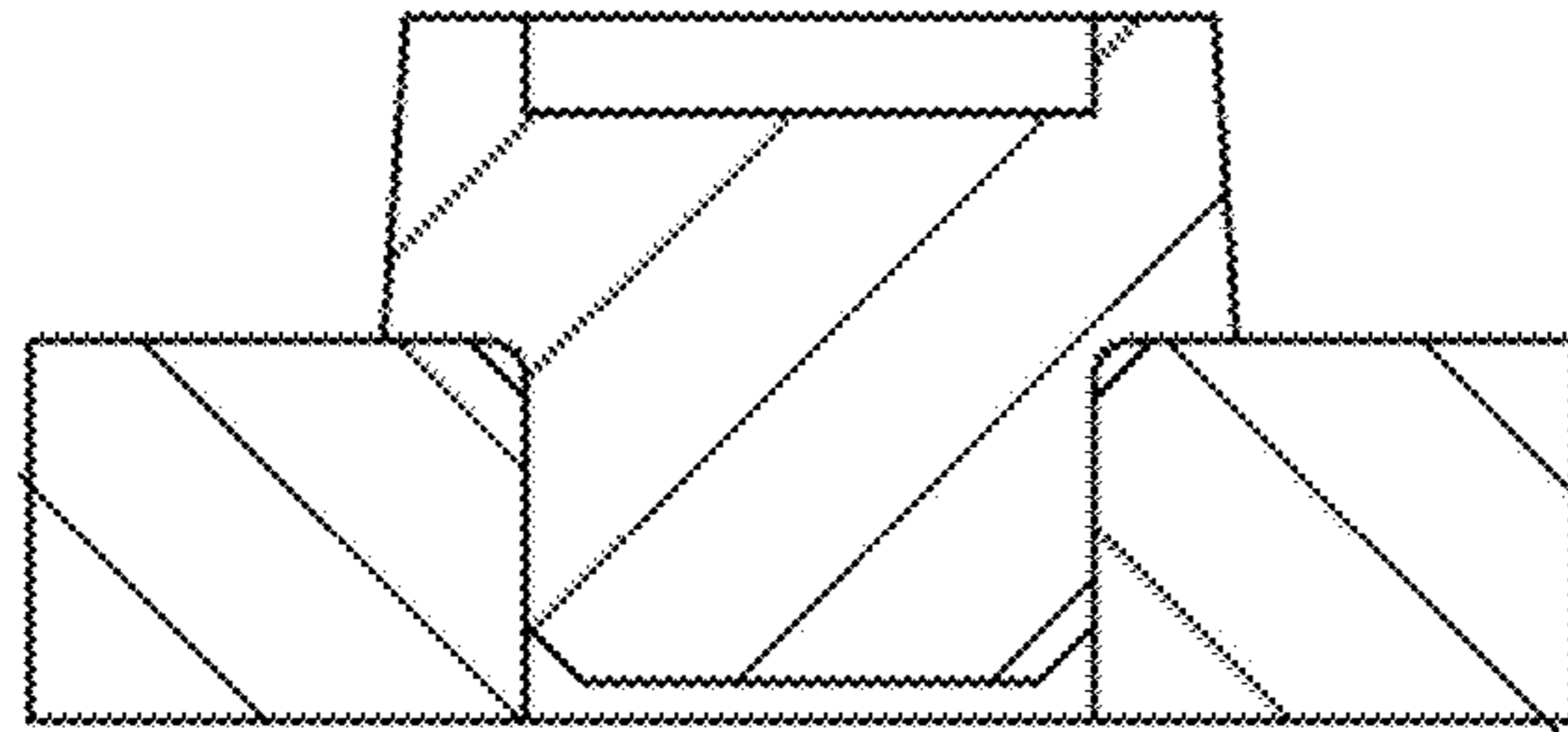


FIG. 7

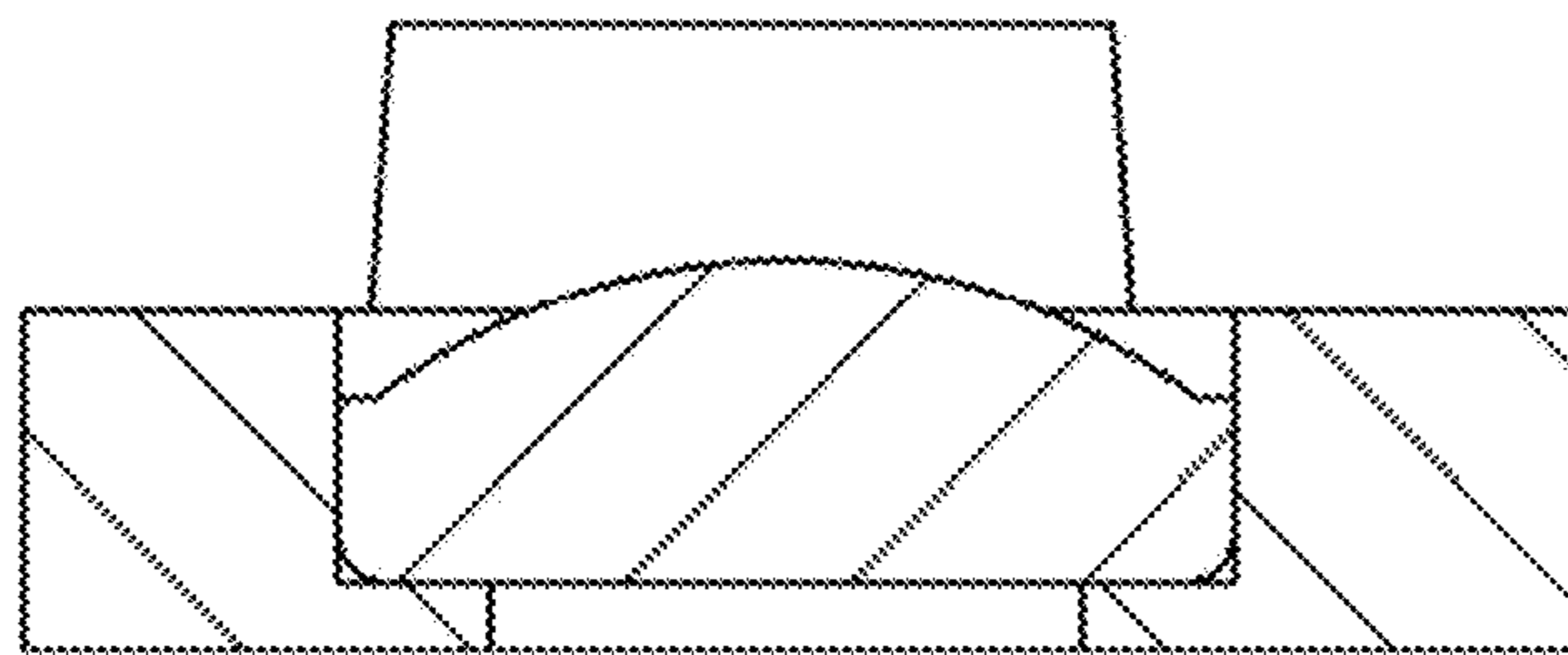


FIG. 8